

BB02-NP :- 1.27mm (0.05") STRAIGHT SMD FEMALE HEADER, SINGLE ROW - 2 TO 50 CONTACTS, DUAL ENTRY

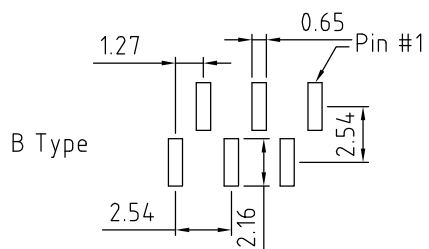
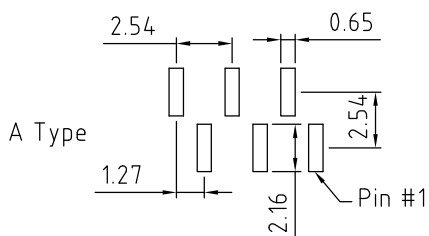
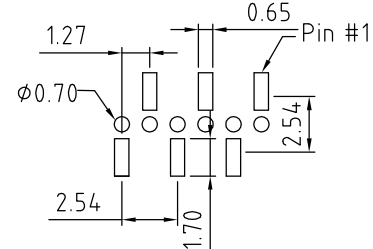
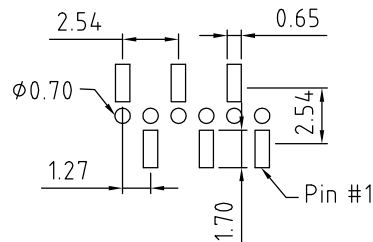
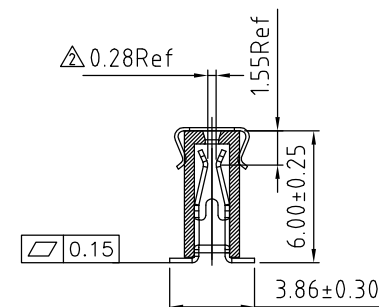
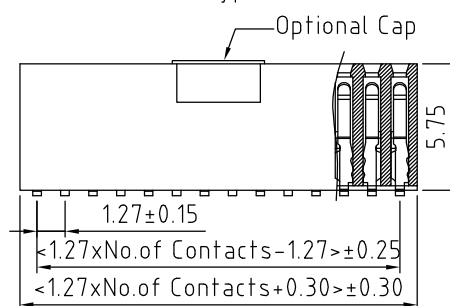
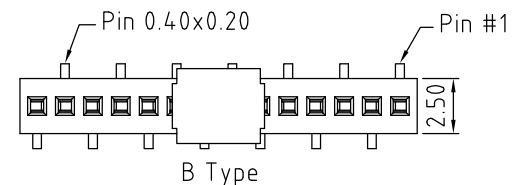
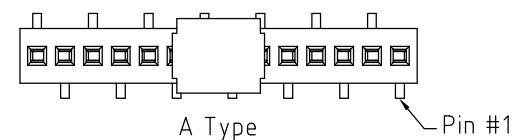
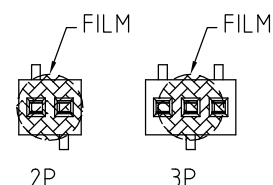
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	300 V AC/DC
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0
	STANDARD: LCP OR EQUIVALENT
PLATING	GOLD, TIN OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC
	MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:

1. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 4.0MM.
2. PARTS WITH SMALL PIN NUMBERS MIGHT BE PACKED IN BOX INSTEAD OF TUBE.

MATES WITH: - (0.46 SQUARE PINS)
BB02-BL BB02-NH
BB02-BM BB02-NM

RECOMMENDED PCB LAYOUT FOR TOP ENTRY
(TOLERANCE: ±0.05)RECOMMENDED PCB LAYOUT FOR BOTTOM ENTRY
(TOLERANCE: ±0.05)

HOW TO ORDER

BB02 - NPXX2 - XXX - 0000000

NO. OF CONTACTS:
02 TO 50

FOOTPRINT TYPE:
A = A TYPE
B = B TYPE

CONTACT PLATING OPTIONS:

K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL

PACKAGING OPTIONS:

3 = TUBE
5 = TUBE + CAP (or FILM for 2 & 3 pins)
6 = TAPE & REEL
8 = TAPE & REEL + CAP (or FILM for 2 & 3 pins)
(SEE NOTE 2.)

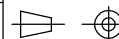
Scale: 5:1

Drawn: NYW

App'd: XXXX

Date: 24 OCT. '14

THIRD ANGLE



Title SOCKET

Revision: 1.2

Unstated Tolerances:
X ± 0.30
X ± 0.25
XX ± 0.15
XXX ± 0.10

Material
SEE NOTE

NOT TO SCALE

UNIT: mm



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Type: BB02-NP

BB02-NP

Drawing Number:

Sheet 1 of 1

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